

RE 5/1/09  
4/16/09

Form PTO-1595 (Rev. 08/05)  
OMB No. 0651-0027 (exp. 6/30/2008)

05-05-2009

U.S. DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office



IEET

103559107

6737-99

2

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Silicon Valley Bank

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) April 3, 2009

- Assignment
- Security Agreement
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other Release
- Merger
- Change of Name

2. Name and address of receiving party(ies)

Name: Antares Advanced Test  
Internal Address: Technologies, Inc.

Street Address: 1501 Richland Ave.

City: Kansas City

State: KS

Country: USA Zip: 66106

Additional name(s) & address(es) attached?  Yes  No

4. Application or patent number(s):

A. Patent Application No.(s)

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Laura Konrath

Internal Address: Winston & Strawn LLP

Street Address: 35 W. Wacker Dr.

City: Chicago

State: IL Zip: 60601

Phone Number: 312-558-6352

Fax Number: 312-558-5700

Email Address: lkonrath@winston.com

6. Total number of applications and patents involved: 37

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 1,480

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_

b. Deposit Account Number 232428

Authorized User Name Laura Konrath

9. Signature:

*Laura Konrath*  
Signature  
Laura Konrath  
Name of Person Signing

*4/16/09*  
Date

Total number of pages including cover sheet, attachments, and documents:

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

ORIGINAL

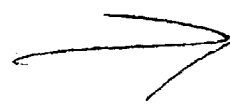
# Continuation Item 4

- 8. SAC 105 Solution
- 9. Standardized Molded Lids
- 10. Intel : Lever Lid System
- 11. Materials qual (Tecalpek + MDS100)
- 12. Intel Cleaning /Socket Cleaning
- 13. Standardized Heatsinks for Lids
- 14. Gasher Nehalem Interposer
- 15. Prestress Contactor System (Penwell)
- 16. Products developed under the Phoenix Test Array- elastomer project (a/k/a Polaris), subject to the underlying rights of Phoenix Test Arrays LLC. However, the Letter of Intent between Antares Advanced Test Technologies, Inc. and Phoenix Test Arrays, LLC dated February 24, 2009 is not a Purchased Asset and will be retained by Seller.
- 17. Products developed under the Plastronics "H" Pin License, subject to the underlying rights of Plastronics in the Plastronics "H" Pin License, which is not a Purchased Asset and will be retained by Seller.

### Patents

Docket No. Case Type	Title Short Title	Country App. No. Grant No.	Status App. Date Grant Date	
0.3100 9606-201 National Patent	APPARATUS FOR TESTING A NONPACKAGED DIE	United States 08/060,614 5,656,945	Granted 5/12/1993 8/12/1997	U.S.
0.0100 9606-202 Design	SHEET METAL INTERCONNECT ARRAY	United States 29/194,881 D525,207	Granted 12/2/2003 7/18/2006	U.S.
0.0200 9606-203 National Patent	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	United States 10/700,401 6,890,185	Granted 11/03/2003 5/10/2005	U.S.
0.0217 9606-204 Continuation	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	United States 11/125,035 7,217,138	Granted 5/9/2005 5/15/2007	9606-203 United States 11/3/2003 10/700,401 U.S.
0.0216				

Grant No. Grant Date



5

9606-206  
PCT  
Application

MULTIPATH  
INTERCONNECT WITH  
MEANDERING CONTACT  
CANTILEVERS

WO  
PCT/US2004/028200

Granted National  
8/31/2004

9606-203  
United States  
11/3/2003  
10/700,401

U.S.

0.02117  
9606-205  
PCT Nat'l  
Phase

MULTIPATH INTERCONNECT  
WITH MEANDERING CONTACT  
CANTILEVERS

Korea  
2006-7010770

Pending  
8/31/2004

9606-203  
United States  
11/3/2003  
10/700,401  
9606-206  
PCT  
8/31/2004  
PCT/US2004/028200

6

0.0300  
9606-210  
National Patent

SEE-SAW INTERCONNECT  
ASSEMBLY WITH  
DIELECTRIC CARRIER GRID  
PROVIDING SPRING SUSPENSION

United States  
10/759,338  
7,059,865

Granted  
1/16/2004  
6/13/2006

U.S.

0.0393  
9606-211

SEE-SAW INTERCONNECT  
ASSEMBLY WITH  
DIELECTRIC CARRIER GRID  
PROVIDING SPRING SUSPENSION

Malaysia  
PJ20043549

Pending  
8/18/2004

9606-210  
United States  
1/16/2004  
10/759,338

7

0.0316  
9606-213  
PCT Application

SEE-SAW INTERCONNECT  
ASSEMBLY WITH  
DIELECTRIC CARRIER GRID  
PROVIDING SPRING SUSPENSION

WO  
PCT/US2004/  
028126

Granted National  
8/18/2004

9606-210  
United States  
1/16/2004  
10/759,338

US

8

0.0317  
9606-214  
Continuation

SEE-SAW INTERCONNECT  
ASSEMBLY WITH  
DIELECTRIC CARRIER GRID  
PROVIDING SPRING SUSPENSION

United States  
11/077,054  
7,189,078

Granted  
3/10/2005  
3/13/2007

9606-210  
United States  
1/16/2004  
10/759,338

US

9

0.0400  
9606-215  
National Patent

TEST SOCKET FOR AN IC  
DEVICE

United States  
08/538,956  
6,046,597

Granted  
10/4/1995  
4/4/2000

US

10

0.0417  
9606-216  
Divisional

TEST SOCKET FOR AN IC  
DEVICE

United States  
09/552,138  
6,559,665

Granted  
4/4/2000  
5/6/2003

9606-215  
United States  
10/4/1995  
08/538,956

U.S.

0.0500

08/538,956 10/4/1995

9606-217  
Continuation-in-  
Part

COVER ASSEMBLY FOR AN  
IC SOCKET

United States  
09/272,629  
6,354,859

Granted  
3/18/1998  
3/12/2002

United States  
3/18/1998  
60/078,525  
9606-215  
United States  
10/4/1995  
08/538,956

US

0.0600  
9606-218  
National Patent

IC CHIP SOCKET AND  
METHOD

United States  
09/032,361  
6,220,870

Granted  
2/27/1998  
4/24/2001

US

0.0700  
9606-219  
National Patent

PROBE TIP AND METHOD  
FOR MAKING ELECTRICAL  
CONTACT WITH A SOLDER  
BALL CONTACT OF AN  
INTEGRATED CIRCUIT  
DEVICE

United States  
09/014,100  
6,208,155

Granted  
1/27/1998  
3/27/2001

US

0.0800  
9606-220  
National Patent

CONNECTOR, CONNECTOR  
SYSTEM AND METHOD OF  
MAKING A CONNECTOR

United States  
09/049,802  
6,042,387

Granted  
3/27/1998  
3,28,2000

US

0.0900  
9606-221  
National Patent

TEST SOCKET AND  
METHOD FOR TESTING AN  
IC DEVICE IN A DEAD BUG  
ORIENTATION

United States  
09/602,924  
6,297,654

Granted  
6/22/2000  
10/2/2001

United States  
7/14/1999  
60/144,059

US

0.1000  
9606-222  
National Patent

BUTTON CONTACT FOR  
SURFACE MOUNTING AN IC  
DEVICE TO A CIRCUIT  
BOARD

United States  
08/531,367  
5,629,837

Granted  
9/20/1995  
5/13/1997

US

0.1220  
9606-225  
National Patent

MODULAR  
SEMICONDUCTOR  
PACKAGE TESTING PROBE  
CONTACTOR SYSTEM

Taiwan  
94123694

Pending  
7/13/2005

9606-226  
United States  
7/14/2004  
60/587,761

0.1250  
9606-226  
Provisional  
Application

MODULAR CONTACTOR  
SYSTEM, SPRING PROBE  
BASED

United States  
60/587,761

Completed  
7/14/2004

US

0.1200  
9606-228  
National Patent

MODULAR  
SEMICONDUCTOR  
PACKAGE TESTING  
CONTACTOR SYSTEM

United States  
11/177,673  
7,189,092

Granted  
7/8/2005  
3/13/2007

9606-226  
United States  
7/14/2004  
60/587,761

US

19	See 0.1750 9606-234 National Patent	ACTIVE TEST SOCKET	United States 11/671,963	Pending 2/6/2007	9606-234 United States 2/6/2006 60/765,553
20	0.1750 9606-234 Provisional Application	ACTIVE TEST SOCKET	United States 60/765,555	Completed 2/6/2006	
21	See 0.1500 9606-235 National Patent	INTERCONNECT ASSEMBLY FOR A PROBE CARD	United States 11/198,995 7,217,139	Granted 8/8/2005 5/15/2007	United States 8/11/2004 60/600,512
22	0.1516 9606-237 PCT Application	INTERCONNECT ASSEMBLY FOR A PROBE CARD	WO PCT/US2005/028240	Gone National 8/9/2005	United States 8/11/2004 60/600,512
23	0.1850 9606-241 National Patent	COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 11/671,942	Pending 2/6/2007	9606-214 United States 2/6/2006 60/765,710
24	0.1850 9606-241 Provisional Application	COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 60/765,710	Completed 2/6/2006	
25	See 0.1950 9606-242 National Patent	CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 11/671,986 7,297,004	Granted 2/6/2007 11/20/2007	9606-242 United States 2/6/2006 60/765,549
26	0.1950 9606-242 Provisional Application	CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 60/765,549	Completed 2/6/2006	
27	See 0.2250 9606-245 National Patent	MICRO- COAX/COMPRESSIBLE CONDUCTOR CONTACTOR	United States 11/675/521	Pending 2/15/2007	9606-245 United States 2/21/2006 60/775,301
	0.2250				

28

9606-245  
Provisional  
Application

MICRO-  
COAX/COMPRESSIBLE  
CONDUCTOR CONTACTOR

United States  
60/775,301

Completed  
2/21/2006

29

0.2550  
9606-248  
Provisional  
Application

INTERCONNECT ASSEMBLY  
FOR TESTING INTEGRATED  
CIRCUIT PACKAGES

United States  
60/735,937

Completed  
11/10/2005

30

0.2750  
9606-250  
Provisional  
Application

INTERCONNECT ASSEMBLY  
FOR TESTING INTEGRATED  
CIRCUIT PACKAGES

United States  
60/735,939

Completed  
11/10/2005

31

0.3000  
9606-253  
National Patent

BUNDLE PROBE  
APPARATUS FOR MULTIPLE  
TERMINAL CONTACT

United States  
09/775,676  
7,064,564

Granted  
2/1/2001  
6/20/2006

~~9606-256  
PCT Nat'l Phase~~

~~SEE-SAW INTERCONNECT  
ASSEMBLY WITH  
DIELECTRIC CARRIER GRID  
PROVIDING SPRING  
SUSPENSION~~

~~China  
200480043418.3~~

~~Pending  
8/30/2004~~

~~9606-210  
United States  
1/16/2004  
10/759,338  
9606-213  
PCT  
8/30/2004  
PCT/US2004/028126~~

32

9606-258  
National Patent

INTERCONNECT ASSEMBLY  
FOR TESTING INTEGRATED  
CIRCUIT PACKAGES

United States  
11/558,591

Pending  
11/10/2006

9606-248  
United States  
11/10/2005  
60/735,937

33

9606-260  
National Patent

INTERCONNECT ASSEMBLY  
FOR TESTING INTEGRATED  
CIRCUIT PACKAGES

United States  
11/558,603  
7,402,051

Granted  
11/10/2006  
7/22/2008

9606-250  
United States  
11/10/2005  
60/735,939

~~9606-264  
PCT Nat'l Phase~~

~~INTERCONNECT ASSEMBLY  
FOR A PROBE CARD~~

~~China  
200580026854.6~~

~~Pending  
8/9/2005~~

~~United States  
8/11/2004  
60/600,512  
9606-237  
United States  
PCT  
8/9/2005  
PCT/US2005/028240~~

9606-266 INTERCONNECT ASSEMBLY FOR A PROBE CARD  
 PCT Nat'l Phase

Korea  
2007-7004850

Pending  
8/9/2005

United States  
8/11/2004  
60/600/512  
9606-237  
8/9/2005  
PCT/US 2005/028240

9606-267 INTERCONNECT ASSEMBLY FOR A PROBE CARD  
 PCT Nat'l Phase

Philippines  
2007-500334

Pending  
8/9/2005

United States  
8/11/2005  
60/600/512  
9606-237  
United States  
8/9/2005  
PCT/US 2005/028240

34 9606-284 TEST INTERCONNECT  
 National Patent

United States  
12/054,281

Pending  
3/24/2008

35 9606-286 IMPEDANCE-MATCHED TEST SOCKET AND METHOD OF MANUFACTURING SAME  
 Provisional Application

United States  
61/022,675

Pending  
1/22/2008

36 9606-288 IMPEDANCE-MATCHED TEST SOCKET OF MANUFACTURING SAME  
 Provisional Application

United States  
61/038/614

Pending  
3/21/2008

37 9606-289 SPRING PROBE  
 National Patent

United States  
12/105,922

Pending  
4/18/2008

37

USPTO

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PAGE 3/019

Fax Server

TO: LAURA KONRATH COMPANY: WINSTON & STRAWN LLP

Winston & Strawn

4/16/2009 4:38:27 PM

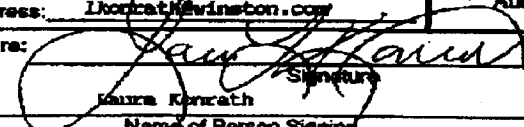
PAGE 003/017

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04/16/2009  
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Form PTO-1595 (Rev. 06/05)  
OMB No. 0651-0027 (exp. 6/30/2008)

U.S. DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET PATENTS ONLY <u>6737-99</u> <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">2</span>	
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.	
<b>1. Name of conveying party(ies)</b> Silicon Valley Bank  Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	<b>2. Name and address of receiving party(ies)</b> Name: <u>Antares Advanced Test</u> Internal Address: <u>Technologies, Inc.</u>  Street Address: <u>1501 Rickland Ave.</u>  City: <u>Kansas City</u> State: <u>KS</u> Country: <u>USA</u> Zip: <u>66106</u>  Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
<b>3. Nature of conveyance/Execution Date(s):</b> Execution Date(s) <u>April 3, 2009</u> <input type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input checked="" type="checkbox"/> Other <u>Release</u>	<b>4. Application or patent number(s):</b> <input type="checkbox"/> This document is being filed together with a new application. A. Patent Application No.(s)  B. Patent No.(s)  Additional numbers attached? <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
<b>5. Name and address to whom correspondence concerning document should be mailed:</b> Name: <u>Laura Konrath</u> Internal Address: <u>Winston &amp; Strawn LLP</u>  Street Address: <u>35 W.acker Dr.</u>  City: <u>Chicago</u> State: <u>IL</u> Zip: <u>60601</u> Phone Number: <u>312-558-6352</u> Fax Number: <u>312-558-5700</u> Email Address: <u>Lkonrath@winston.com</u>	<b>6. Total number of applications and patents involved:</b> <u>37</u>  <b>7. Total fee (37 CFR 1.21(h) &amp; 3.41) \$ 1,480</b> <input type="checkbox"/> Authorized to be charged by credit card <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title)
<b>9. Signature:</b>  Name of Person Signing: <u>Laura Konrath</u>	<b>8. Payment information</b> a. Credit Card Last 4 Numbers _____ Expiration Date _____ b. Deposit Account Number <u>232428</u> Authorized User Name <u>Laura Konrath</u> Date <u>4/16/09</u>  Total number of pages including cover sheet, attachments, and documents: <input type="checkbox"/>

Documents to be recorded (including cover sheet) should be filed in (807) 273-0148, or mailed to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1448, Alexandria, VA 22313-1448

Additional numbers attached  Yes  No

8. Payment information



2

ACKNOWLEDGMENT OF AMENDMENT TO  
INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Acknowledgment of Amendment to Intellectual Property Security Agreement (the "Release") is made with reference to that certain Intellectual Property Security Agreement dated September 1, 2006 (the "IP Agreement") by and between ANTARES ADVANCED TEST TECHNOLOGIES, INC., a Washington corporation ("AATT") and SILICON VALLEY BANK ("Silicon"). The IP Agreement was recorded in the United States Copyright Office on December 16, 2008 with respect to the items set forth on Exhibit A thereto. The IP Agreement was recorded in the United States Patent and Trademark Office on October 23, 2006 with respect to the patent items set forth on Exhibit B thereto.

Silicon hereby acknowledges and agrees that the IP Agreement is hereby amended to release, terminate and cancel all of Silicon's security interests and liens in the intellectual property identified on Schedule 1 attached hereto (the "Released IP") and that all of the rights and interests of Silicon to the Released IP have been terminated and released as of the date hereof.

Silicon shall take all further actions, and provide to AATT, its successors, assigns or other legal representatives, all such cooperation and assistance (including, without limitation, the execution and delivery of any and all documents or other instruments), reasonably requested by AATT, its successors or assigns to more fully and effectively effectuate the purposes of this Release, all at the expense of AATT, its successors or assigns.

Silicon does hereby further authorize and consent that this Release may be recorded and indexed by the Register of Copyrights of the United States Copyright Office and the Commissioner of Patents and Trademarks of the United States Patent and Trademark Office.

Dated: April 3, 2009

Silicon Valley Bank

By:   
Title: CLERK

at the expense of AATT, its successors or assigns.

Silicon Valley Bank

**Schedule 1****Released Intellectual Property****Business Unregistered IP****Trademarks**

1. ANTARES
2. ANTARES ADVANCED TEST TECHNOLOGIES
3. Antares Advanced Test Technologies & Design, as shown:



4. QUATRX
5. Z-SOCKET

**Copyrights**

1. Code and content related solely to the Business associated with the websites listed on Schedule 4.12.1
2. Prototype Javascript Library
3. Scriptaculous Javascript
4. Form validation library based on the Prototype libraries
5. PHP scripts for things such as Timezone manipulation, Active Directory access and file upload feedback

**Products Under Development**

1. Coaxial Sockets
2. Homogenous Modular Pin
3. Active Alignment
4. 25 Milliohm Pin
5. Pin Development 326-01/02.
6. High Pin Count Socket System
7. POP Sockets

8. SAC 105 Solution
9. Standardized Molded Lids
10. Intel : Lever Lid System
11. Materials qual (Tecapeek + MDS100)
12. Intel Cleaning /Socket Cleaning
13. Standardized Heatsinks for Lids
14. Gasher Nehalem Interposer
15. Prestress Contactor System (Penwell)
16. Products developed under the Phoenix Test Array- elastomer project (a/k/a Polaris), subject to the underlying rights of Phoenix Test Arrays LLC. However, the Letter of Intent between Antares Advanced Test Technologies, Inc. and Phoenix Test Arrays, LLC dated February 24, 2009 is not a Purchased Asset and will be retained by Seller.
17. Products developed under the Plastronics "H" Pin License, subject to the underlying rights of Plastronics in the Plastronics "H" Pin License, which is not a Purchased Asset and will be retained by Seller.

#### Patents

Docket No. Case Type	Title Short Title	Country App. No. Grant No.	Status App. Date Grant Date
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0.0100 9606-202 Design	SHEET METAL INTERCONNECT ARRAY	United States 29/194,881 D525,207	Granted 12/2/2003 7/18/2006
0.0200 9606-203 National Patent	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	United States 10/700,401 6,890,185	Granted 11/03/2003 5/10/2005
0.0217 9606-204 Continuation	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	United States 11/125,035 7,217,138	Granted 5/9/2005 5/15/2007
0.0216			9606-203 United States 11/3/2003 10/700,401

9606-206 PCT Application	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	WO PCT/US2004/028200	Granted National 8/31/2004	9606-203 United States 11/3/2003 10/700,401
0.02117 9606-209 PCT Nat'l Phase	MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	Korea 2006-7010770	Pending 8/31/2004	9606-203 United States 11/3/2003 10/700,401 9606-206 PCT 8/31/2004 PCT/US2004/028200
0.0300 9606-210 National Patent	SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	United States 10/759,338 7,059,865	Granted 1/16/2004 6/13/2006	
0.0393 9606-211	SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	Malaysia PI20043349	Pending 8/18/2004	9606-210 United States 1/16/2004 10/759,338
0.0316 9606-213 PCT Application	SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	WO PCT/US2004/ 028126	Granted National 8/18/2004	9606-210 United States 1/16/2004 10/759,338
0.0317 9606-214 Continuation	SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	United States 11/077,054 7,189,078	Granted 3/10/2005 3/13/2007	9606-210 United States 1/16/2004 10/759,338
0.0400 9606-215 National Patent	TEST SOCKET FOR AN IC DEVICE	United States 08/538,956 6,046,597	Granted 10/4/1995 4/4/2000	
0.0417 9606-216 Divisional	TEST SOCKET FOR AN IC DEVICE	United States 09/542,131 6,559,665	Granted 4/4/2000 5/6/2003	9606-215 United States 10/4/1995 08/538,956
0.0500				

9606-217 Continuation-in- Part	COVER ASSEMBLY FOR AN IC SOCKET	United States 09/272,629 6,354,859	Granted 3/18/1999 3/12/2002	United States 3/18/1998 60/078,525 9606-215 United States 10/4/1995 08/538,956
0.0600 9606-218 National Patent	IC CHIP SOCKET AND METHOD	United States 09/032,361 6,220,870	Granted 2/27/1998 4/24/2001	
0.0700 9606-219 National Patent	PROBE TIP AND METHOD FOR MAKING ELECTRICAL CONTACT WITH A SOLDER BALL CONTACT OF AN INTEGRATED CIRCUIT DEVICE	United States 09/014,100 6,208,155	Granted 1/27/1998 3/27/2001	
0.0800 9606-220 National Patent	CONNECTOR, CONNECTOR SYSTEM AND METHOD OF MAKING A CONNECTOR	United States 09/049,802 6,042,387	Granted 3/27/1998 3,28,2000	
0.0900 9606-221 National Patent	TEST SOCKET AND METHOD FOR TESTING AN IC DEVICE IN A DEAD BUG ORIENTATION	United States 09/602,924 6,297,654	Granted 6/22/2001 10/2/2001	United States 7/14/1999 60/144,059
0.1000 9606-222 National Patent	BUTTON CONTACT FOR SURFACE MOUNTING AN IC DEVICE TO A CIRCUIT BOARD	United States 08/531,367 5,629,837	Granted 9/20/1995 5/13/1997	
0.1220 9606-225 National Patent	MODULAR SEMICONDUCTOR PACKAGE TESTING CONTACTOR SYSTEM	Taiwan 94123694 United States 09/117,573	Pending 7/13/2005 3/13/2007	9606-226 United States 7/14/2004 60/587,761
0.1250 9606-226 Provisional Application	MODULAR CONTACTOR SYSTEM, SPRING PROBE BASED	United States 60/587,761	Completed 7/14/2004	
0.1200 9606-228 National Patent	MODULAR SEMICONDUCTOR PACKAGE TESTING CONTACTOR SYSTEM	United States 11/177,573 7,189,092	Granted 7/8/2005 3/13/2007	9606-226 United States 7/14/2004 60/587,761

See 0.1750 9606-234 National Patent	ACTIVE TEST SOCKET	United States 11/671,963	Pending 2/6/2007	9606-234 United States 2/6/2006 60/765,555
0.1750 9606-234 Provisional Application	ACTIVE TEST SOCKET	United States 60/765,555	Completed 2/6/2006	
See 0.1500 9606-235 National Patent	INTERCONNECT ASSEMBLY FOR A PROBE CARD	United States 11/198,995 7,217,139	Granted 8/8/2005 5/15/2007	United States 8/11/2004 60/600,512
0.1516 9606-237 PCT Application	INTERCONNECT ASSEMBLY FOR A PROBE CARD	WO PCT/US2005/028240	Gone National 8/9/2005	United States 8/11/2004 60/600,512
0.1850 9606-241 National Patent	COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 11/671,942	Pending 2/6/2007	9606-214 United States 2/6/2006 60/765,710
0.1850 9606-241 Provisional Application	COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 60/765,710	Completed 2/6/2006	
See 0.1950 9606-242 National Patent	CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 11/671,986 7,297,004	Granted 2/6/2007 11/20/2007	9606-242 United States 2/6/2006 60/765,549
0.1950 9606-242 Provisional Application	CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 60/765,549	Completed 2/6/2006	
See 0.2250 9606-245 National Patent	MICRO- COAX/COMPRESSIBLE CONDUCTOR CONTACTOR	United States 11/675/521	Pending 2/15/2007	9606-245 United States 2/21/2006 60/775,301
0.2250				

9606-245 Provisional Application	MICRO- COAX/COMPRESSIBLE CONDUCTOR CONTACTOR	United States 60/775,301	Completed 2/21/2006	
0.2550 9606-248 Provisional Application	INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 60/735,937	Completed 11/10/2005	
0.2750 9606-250 Provisional Application	INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 60/735,939	Completed 11/10/2005	
0.3000 9606-253 National Patent	BUNDLE PROBE APPARATUS FOR MULTIPLE TERMINAL CONTACT	United States 09/775,676 7,064,564	Granted 2/1/2001 6/20/2006	
9606-256 PCT Nat'l Phase	SRE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	China 200480042418.3	Pending 8/30/2004	9606-210 United States 1/16/2004 10/759,338 9606-213 PCT 8/30/2004 PCT/US2004/028126
9606-258 National Patent	INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 11/558,591	Pending 11/10/2006	9606-248 United States 11/10/2005 60/735,937
9606-260 National Patent	INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 11/558,603 7,402,051	Granted 11/10/2006 7/22/2008	9606-250 United States 11/10/2005 60/735,939
9606-264 PCT Nat'l Phase	INTERCONNECT ASSEMBLY FOR A PROBE CARD TERMINAL CONTACT	China 200580026854.6 7,064,564	Pending 8/9/2005 8/20/2006	United States 8/11/2004 60/600,512 9606-237 United States PCT 8/9/2005 PCT/US2005/028240

<b>9606-266</b> PCT Nat'l Phase	<b>INTERCONNECT ASSEMBLY FOR A PROBE CARD</b>	<b>Korea</b> 2007-7004850	<b>Pending</b> 8/9/2005	<b>United States</b> 8/11/2004 60/600,512 9606-237 8/9/2005 PCT/US 2005/028240
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<b>9606-267</b> PCT Nat'l Phase	<b>INTERCONNECT ASSEMBLY FOR A PROBE CARD</b>	<b>Philippines</b> 2007-500354	<b>Pending</b> 8/9/2005	<b>United States</b> 8/11/2005 60/600,512 9606-237 United States 8/9/2005 PCT/US 2005/028240
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<b>9606-284</b> National Patent	<b>TEST INTERCONNECT</b>	<b>United States</b> 12/054,281	<b>Pending</b> 3/24/2008	
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<b>9606-286</b> Provisional Application	<b>IMPEDANCE-MATCHED TEST SOCKET AND METHOD OF MANUFACTURING SAME</b>	<b>United States</b> 61/022,675	<b>Pending</b> 1/22/2008	
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<b>9606-288</b> Provisional Application	<b>IMPEDANCE-MATCHED TEST SOCKET OF MANUFACTURING SAME</b>	<b>United States</b> 61/038/614	<b>Pending</b> 3/21/2008	
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<b>9606-289</b> National Patent	<b>SPRING PROBE</b>	<b>United States</b> 12/105,922	<b>Pending</b> 4/18/2008	
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